



W38_IB & W40_IF Update

Pablo Gomis (IFIC), Felix Mueller (MPP)

pxdtest1: W38_IB

pxdtest8: W40_IF



Minimum Tests Required before glueing

- ✓ • **DHPT HS Links**
 - short scan (to have a reference for later)
 - bias 200 to 250, step 5
 - bias_d 100 to 150, step 5
 - delay 0
- ✓ • **Delays**
- ? • **ADCs optimization using small parameter space**
- ✓ • **Pedestal/noise (1k frames)**
- ✓ • **2bit offset (delay and current source optimization)**
- ✓ • **Pedestal/noise (1k frames)**
- ✓ • **DCD analog common mode correction**
- ✓ • **Pedestal/noise (1k frames)**
 - **Source measurement different regions** (tbd. latest by Lab Framework meeting Tuesday June 11th)
 - ✓ • Threshold 5
 - ✓ • Verify shape of the spectra
 - ✗ ✓ • SNR in different regions
 - Adjust VNSubIn ACMC ✓
- ✗ • **Gated mode: simplified test using manual switch for the VETO and standard DHH firmware** (metho

Commands (not compliant to the coding guidelines):

Pedestals using the MEMDUMP command:

<https://confluence.desy.de/display/BI/Phase+2+PXD9+Module+Testing>



W38_IB

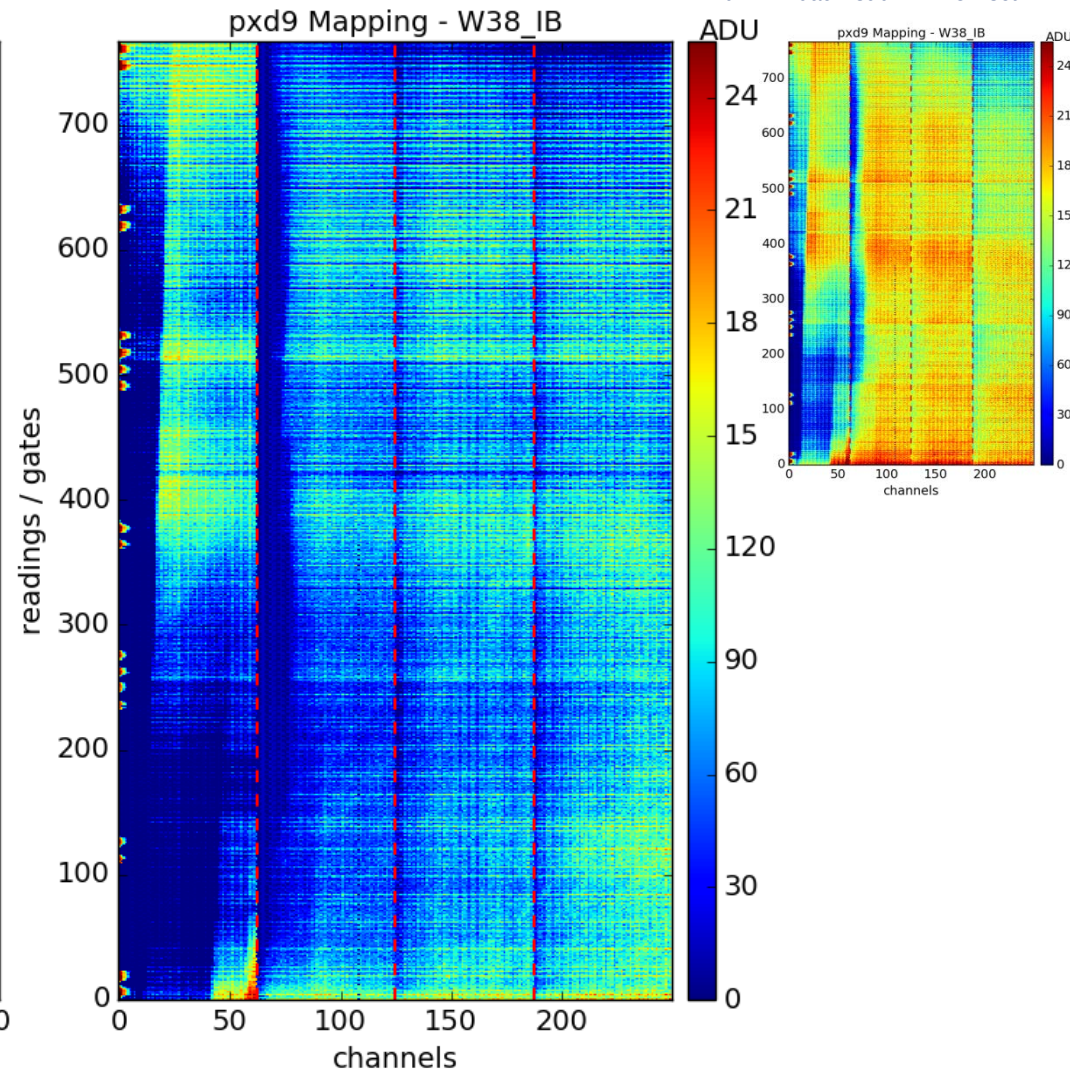
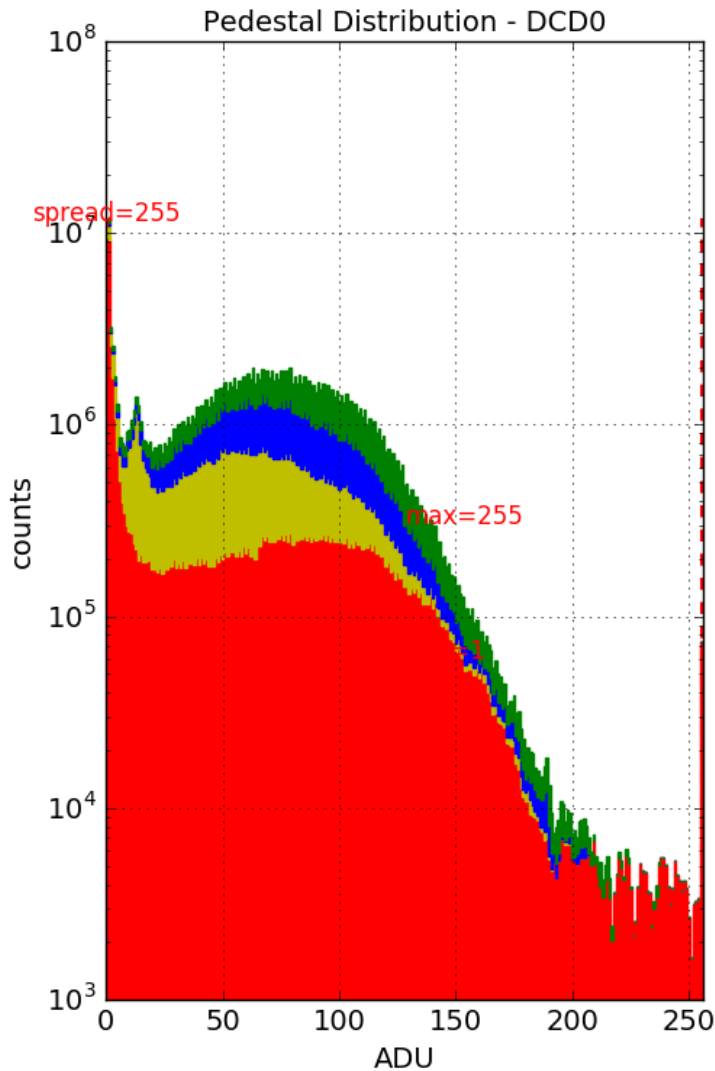


W38_IB – pedestals **without** Offsets and **no** ACMC

already shown on August 2, 2017

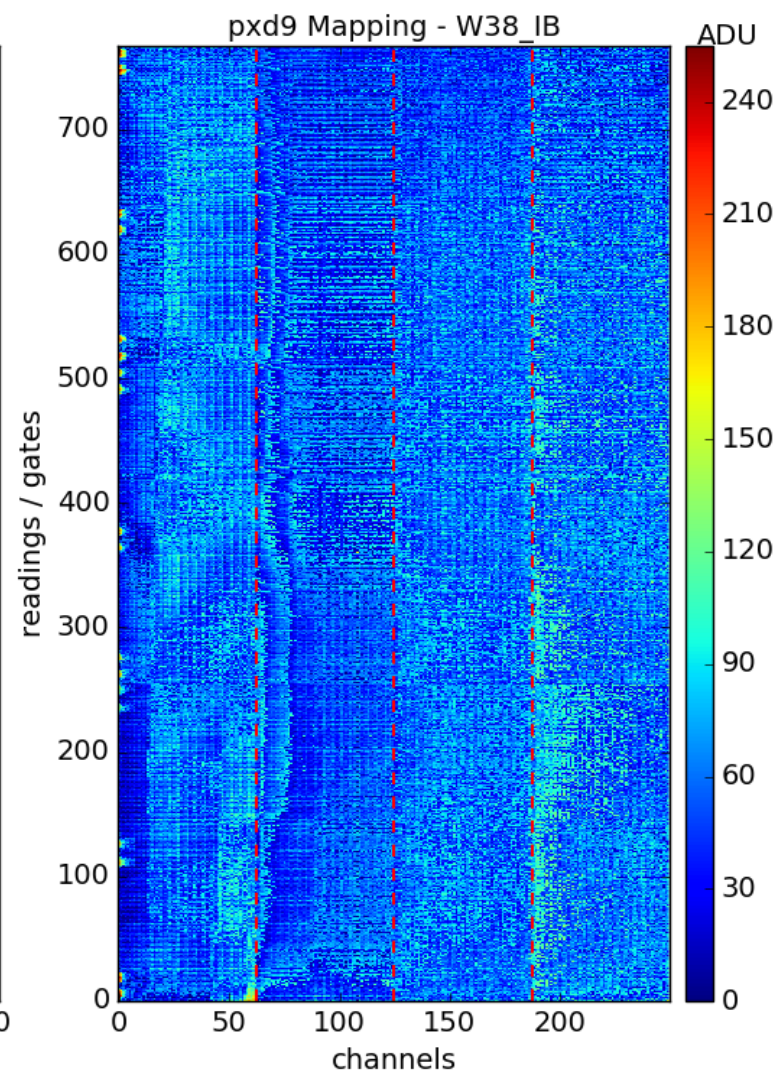
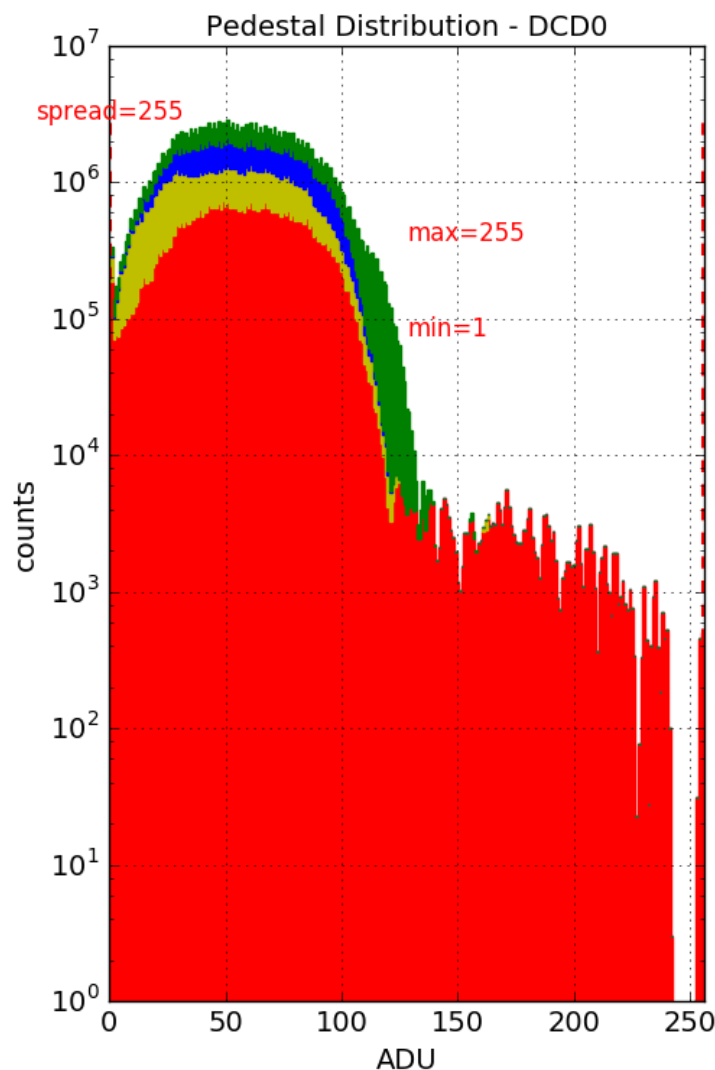
PXD:H1012:R4:dacvnsubin:VALUE:set = 35
PXD:H1012:R2:dacvnsubin:VALUE:set = 32
PXD:H1012:R3:dacvnsubin:VALUE:set = 35
PXD:H1012:R1:dacvnsubin:VALUE:set = 25

PXD:H1012:R4:dacvnsubin:VALUE:set = 33
PXD:H1012:R2:dacvnsubin:VALUE:set = 28
PXD:H1012:R3:dacvnsubin:VALUE:set = 31
PXD:H1012:R1:dacvnsubin:VALUE:set = 22



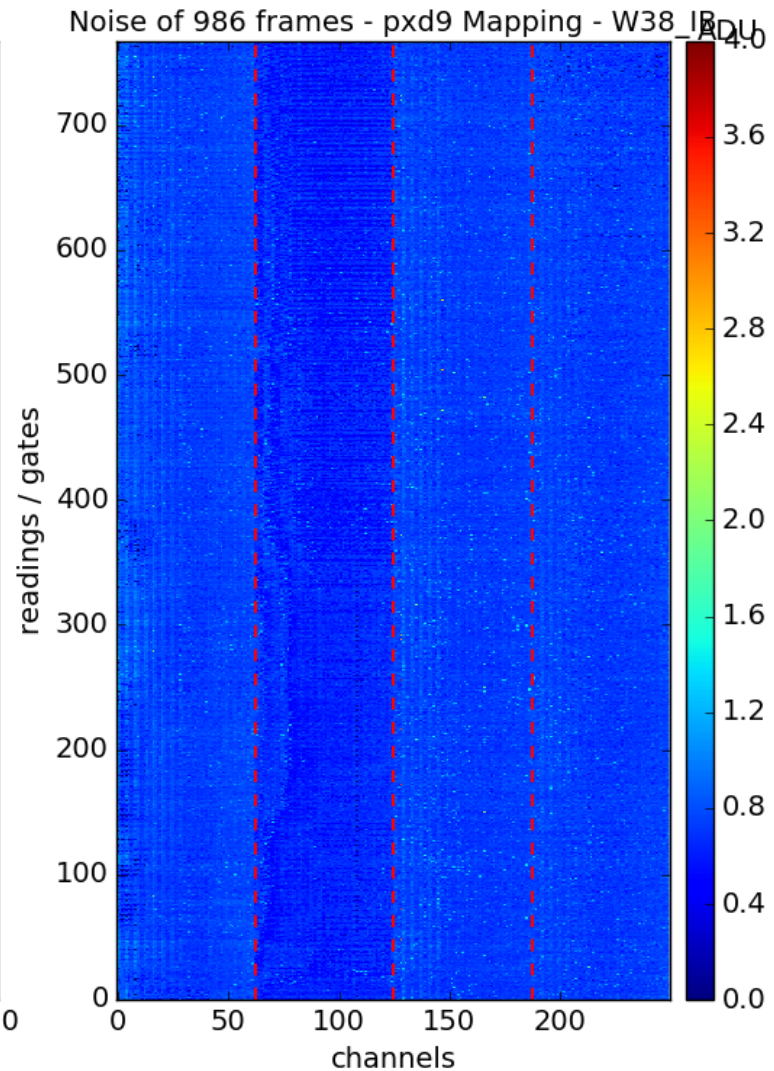
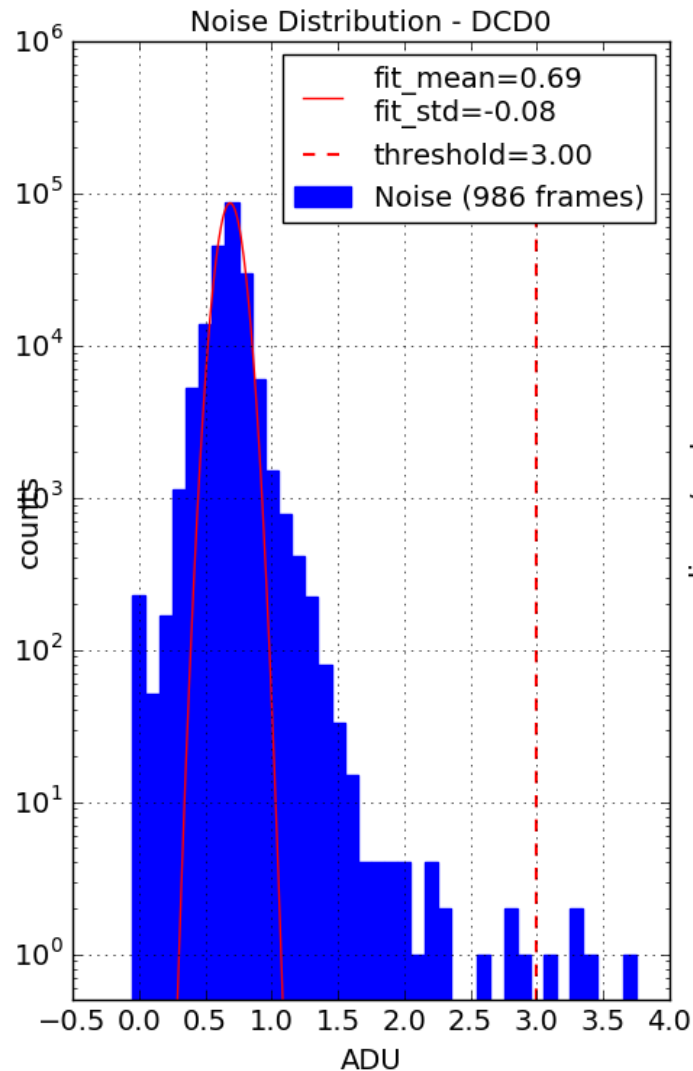


W38_IB – pedestals - with Offsets and ACMC





W38_IB – noise – with Offsets and ACMC





W38_IB – source measurements

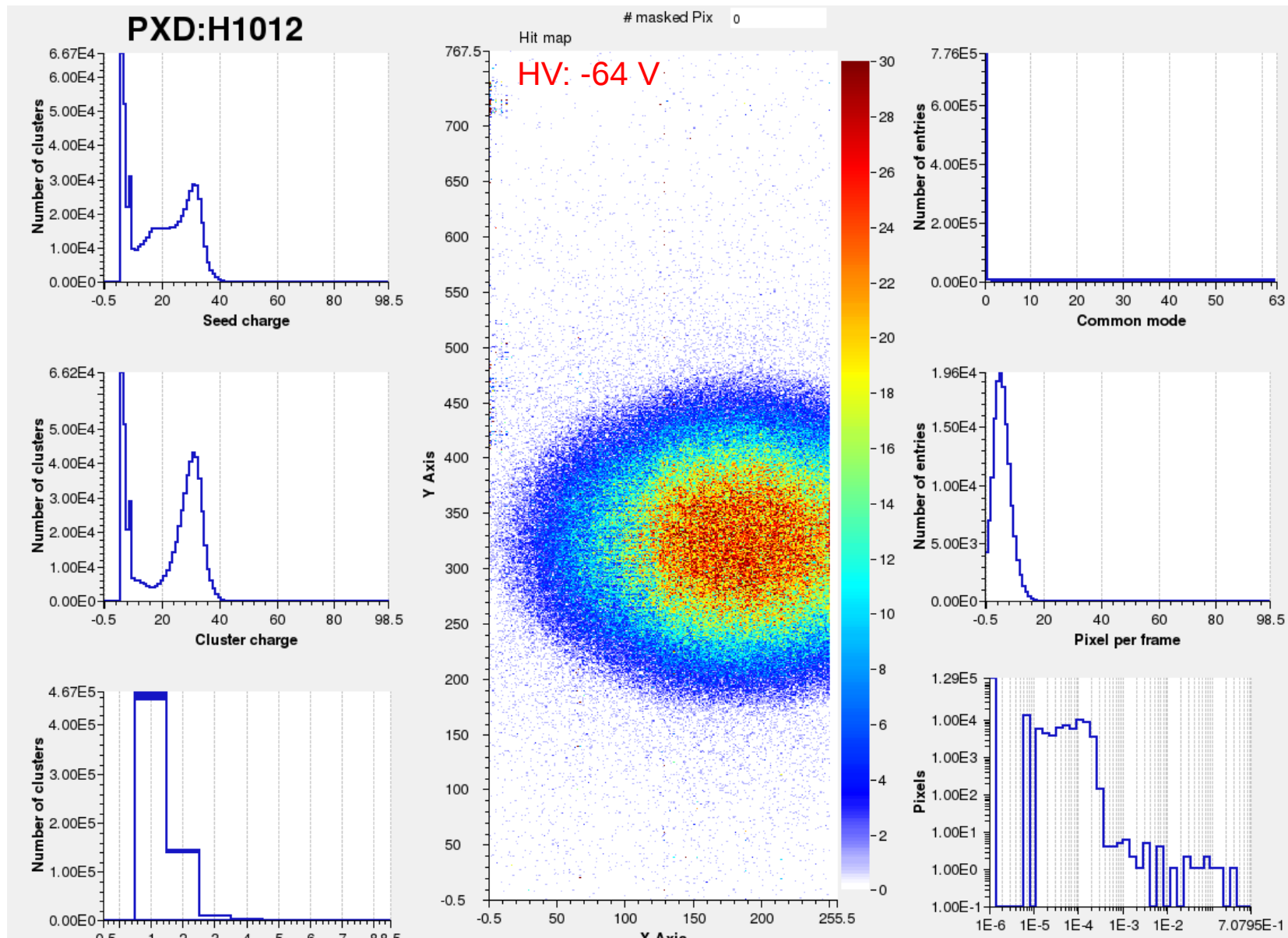
sw-dvdd-voltage 1.798 V, 20 mA
sw-refin-voltage -5.202 V, 0 mA
sw-sub-voltage -7.000 V, -10 mA
dhp-core-voltage 1.198 V, 672 mA
dhp-io-voltage 1.801 V, 290 mA
dcd-amplow-voltage 0.275 V, -702 mA
dcd-avdd-voltage 1.727 V, 2716 mA
dcd-dvdd-voltage 1.800 V, 834 mA
dcd-refin-voltage 0.723 V, 262 mA
bulk-voltage 10.000 V, 0 mA
ccg1-voltage 0.000 V, 0 mA
ccg2-voltage -0.001 V, 0 mA
ccg3-voltage 0.005 V, 0 mA
clear-off-voltage 5.008 V, -20 mA
clear-on-voltage 19.002 V, 27 mA
drift-voltage -5.003 V, 0 mA

gate-off-voltage 2.998 V, 24 mA
gate-on1-voltage -2.500 V, -5 mA
gate-on2-voltage -2.501 V, -5 mA
gate-on3-voltage -2.502 V, -5 mA
guard-voltage -4.999 V, 0 mA
hv-voltage **-70.099 V**, 12 mA
source-voltage 6.002 V, 73 mA

HV scan from -60 V to -80 V (most likely
depending on wafer, e.g. for W30_OB1, -70 V
was the best)

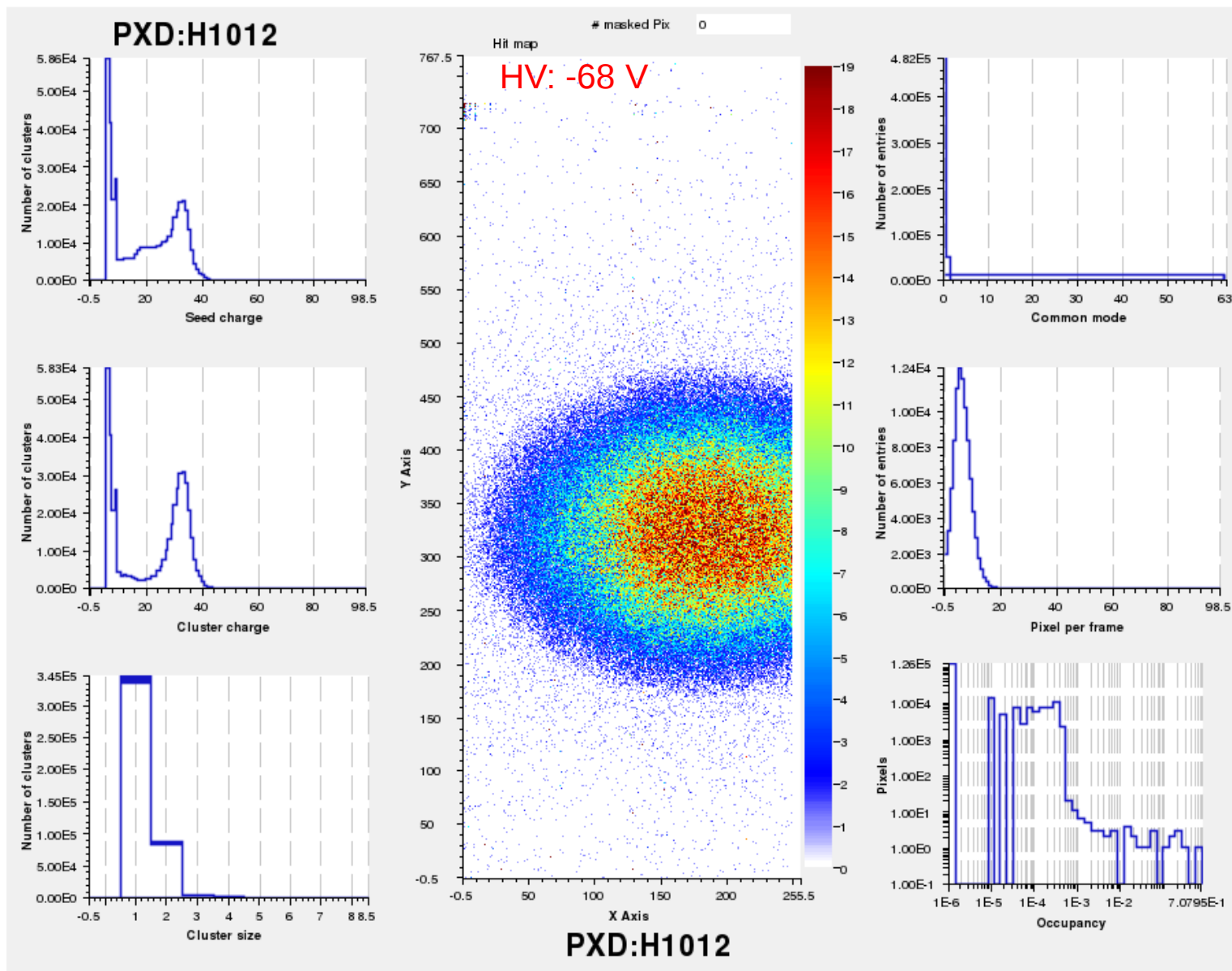


W38_IB – source measurements



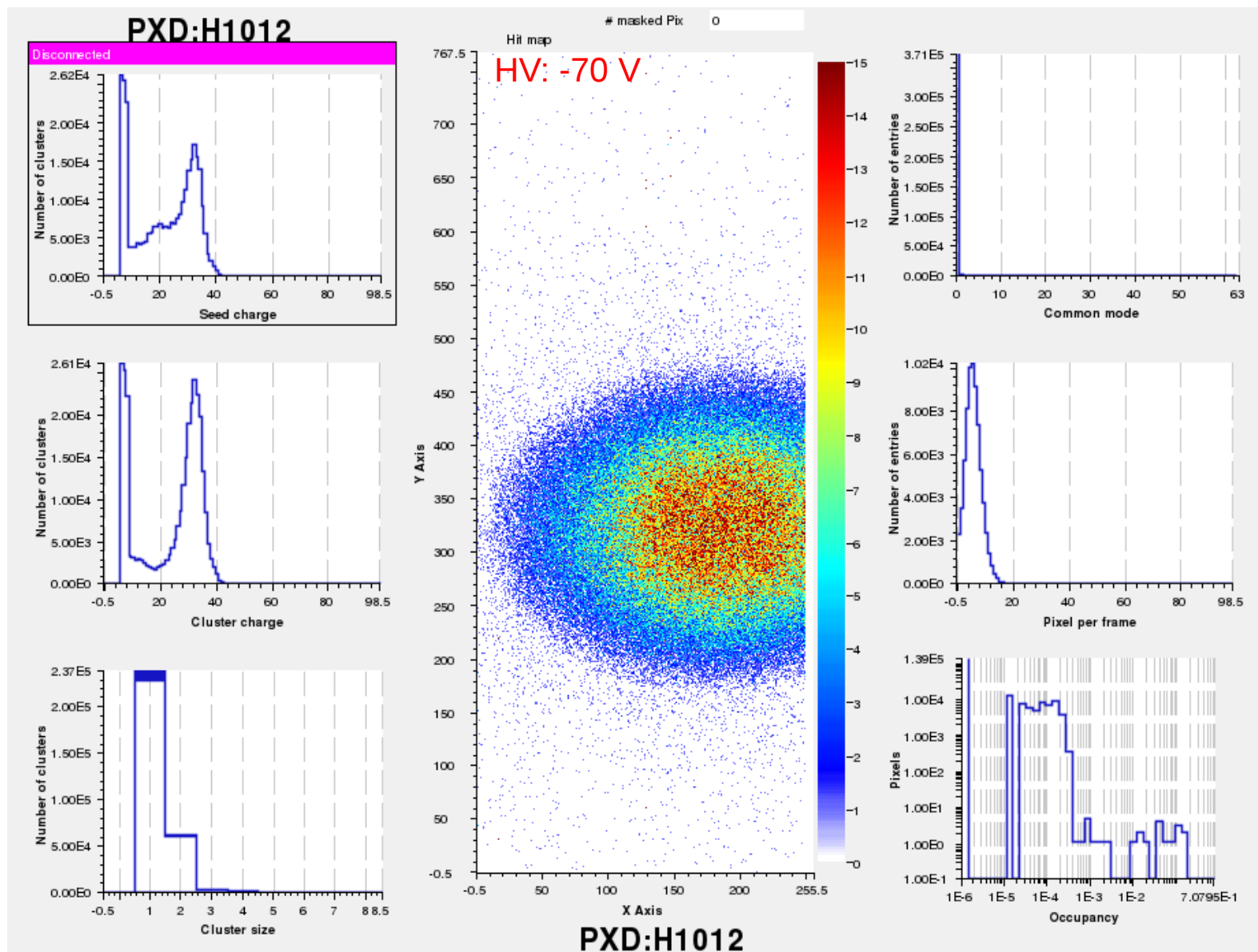


W38_IB – source measurements



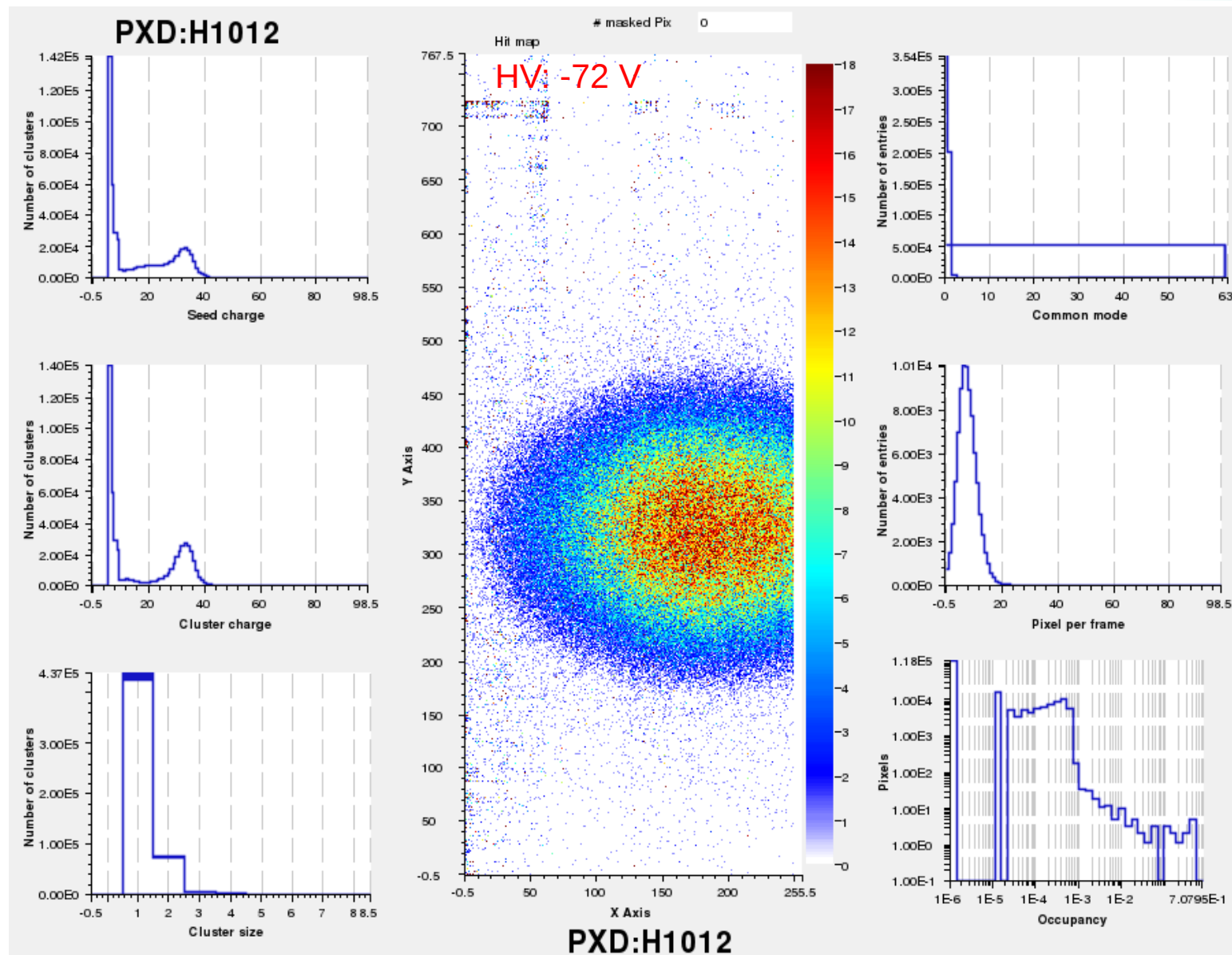


W38_IB – source measurements



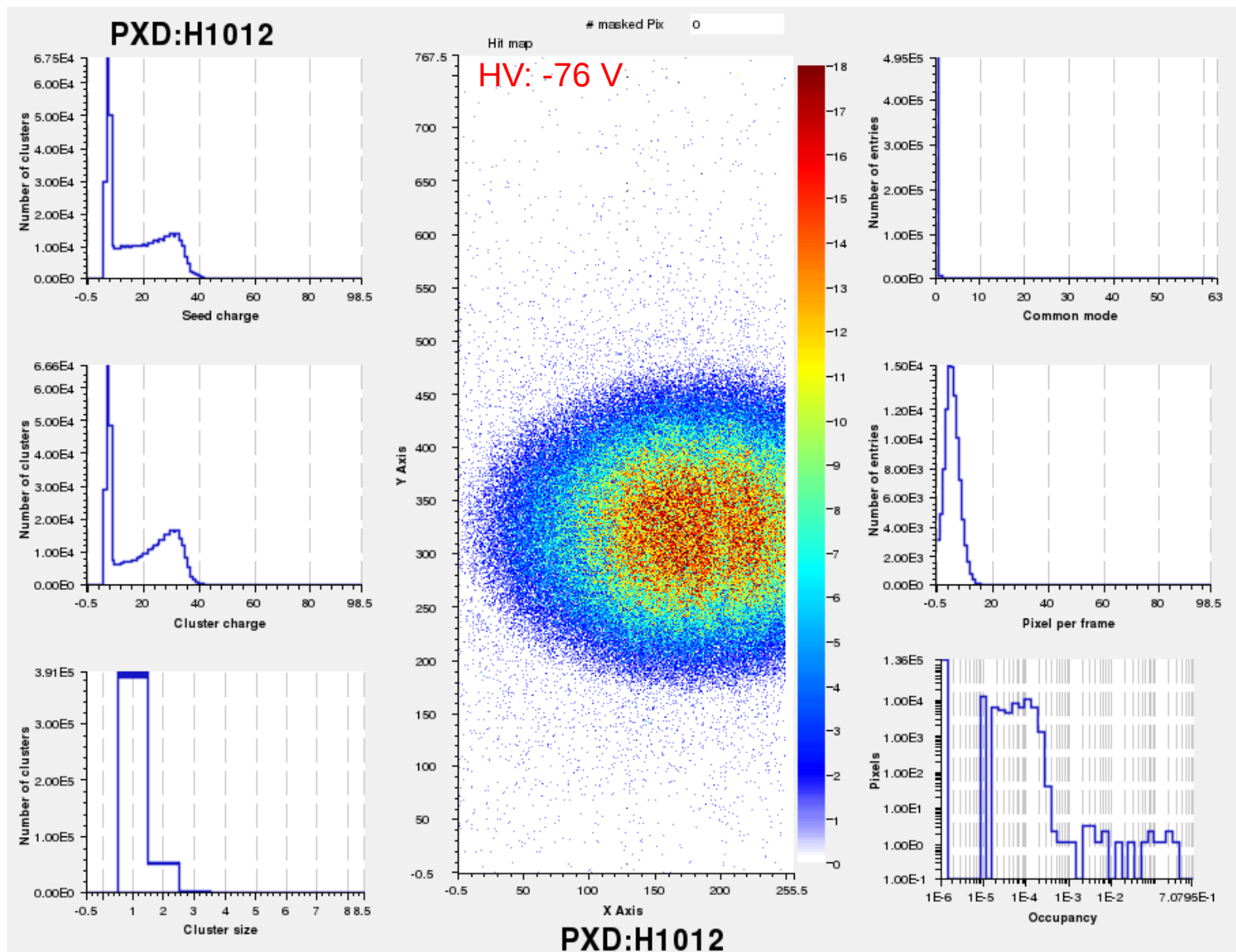


W38_IB – source measurements



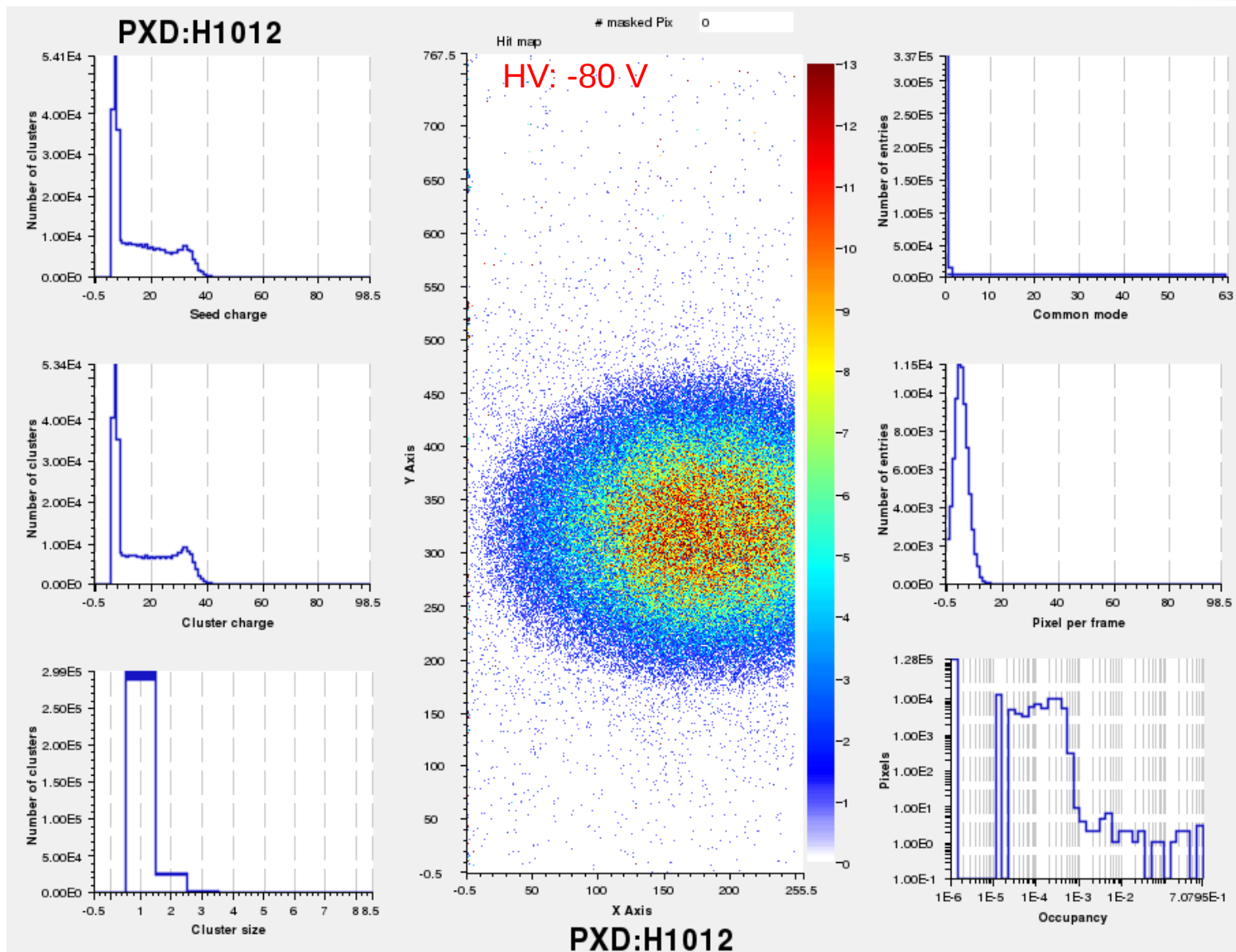


W38_IB – source measurements





W38_IB – source measurements





Glueing

W40_IF & W38_IB have been glued together on Tuesday, August 8, still in the jig
expected to have them back tomorrow (Thursday August 10)

which one for phase 2 ?

Location*	Project*	Item Type	Item Subtype	Item Subtype Version*
In Transfer	Belle II PXD	Module	L1 - Layer1	1 (Prototype) - Belle II PXD
IZM		Pitch Adapter	L2 - Layer2	2 (Production) - Belle II PXD
KEK		Printed Circuit Board		
KIT		PXD Ladder		
LMU Cluster Universe		Readout Electronics		
Mainz		Sensor		
Mannheim		Test structure		
MPP		Wafer		

DEPFET LAB MEETING

9TH AUGUST 2017

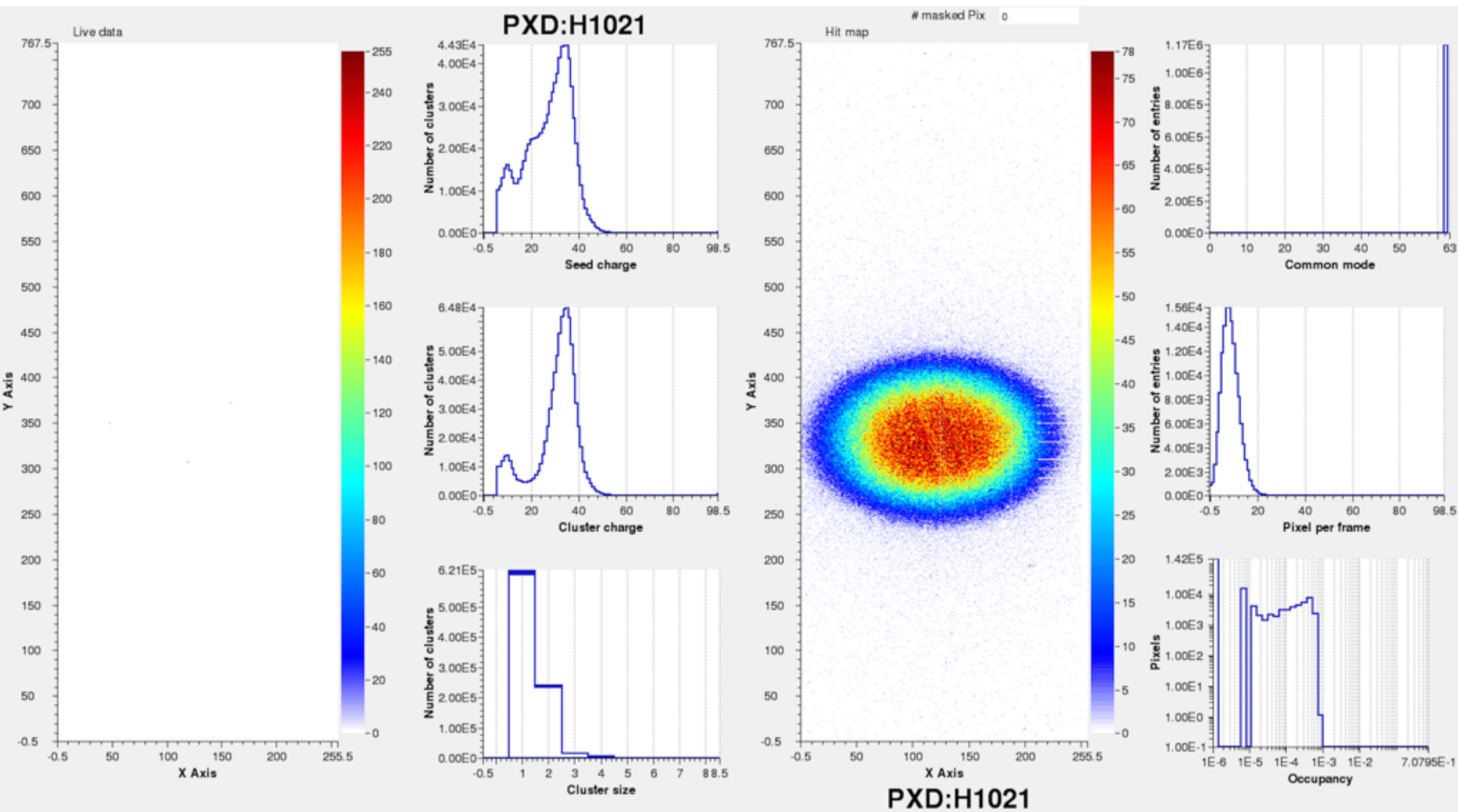
W40_IF SOURCE SCAN

PABLO GOMIS*, FELIX MÜLLER+

* IFIC (UNIVERSITAT DE VALÈNCIA/CSIC)

+ MAX PLANCK INSTITUTE FOR PHYSICS (MPG)

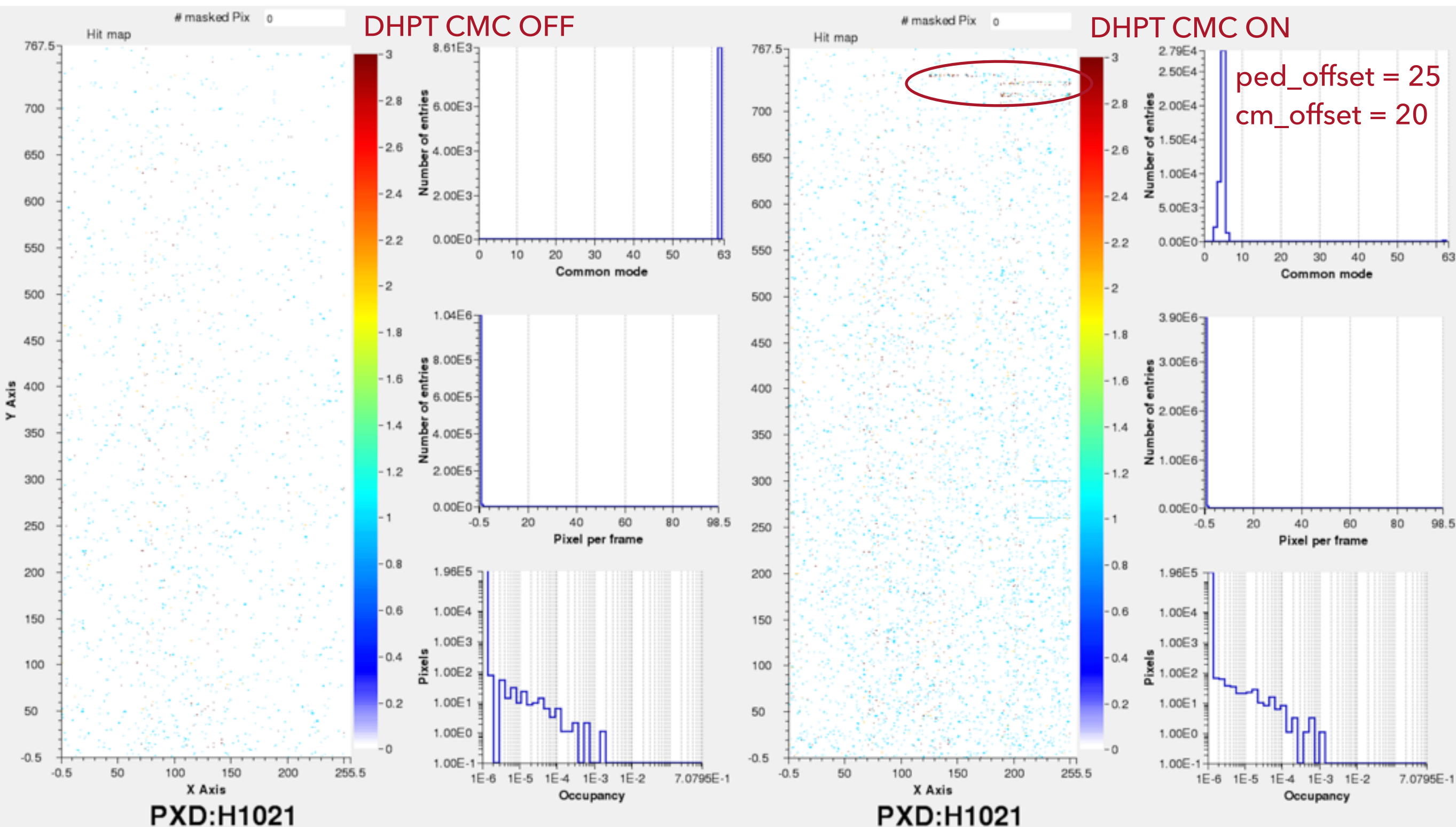
- ▶ pxdtest8
 - ▶ IF lab patch panel
 - ▶ Clamp attached and wide aluminum cooling adaptor
 - ▶ DHP temps checked in between measurements: 55-60°C
 - ▶ Latest DHE firmware (21/06/17 22:00 release)
 - ▶ Source (Cd^{109} , 370MBq @ 15/11/16)
- ▶ Commit ID (#520)
 - ▶ Nominal frequency (76.23 MHz)
 - ▶ Standard values from the template
 - ▶ Optimized delays
 - ▶ Fully stable HSL
 - ▶ DCD ACMC on
 - ▶ 2bit DAC on



- Online monitor used to “analyze” the data, as no scripts are yet available

DHPT CMC: ON VS OFF

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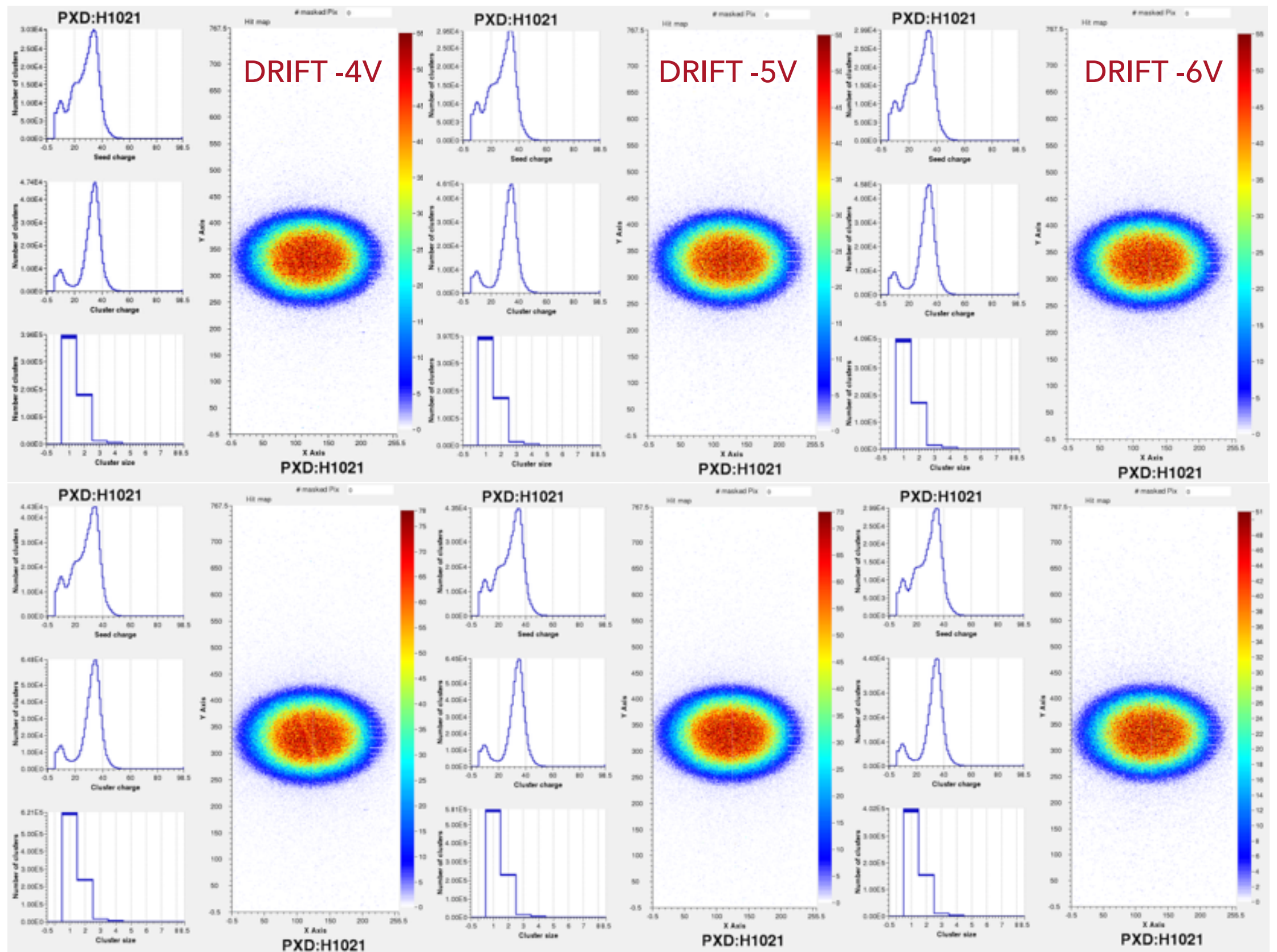


- ▶ When using the "digital" CMC some noisy pixels appear in the hitmaps

VOLTAGE SCAN: HV -56V, -60 V

5

HV -56V

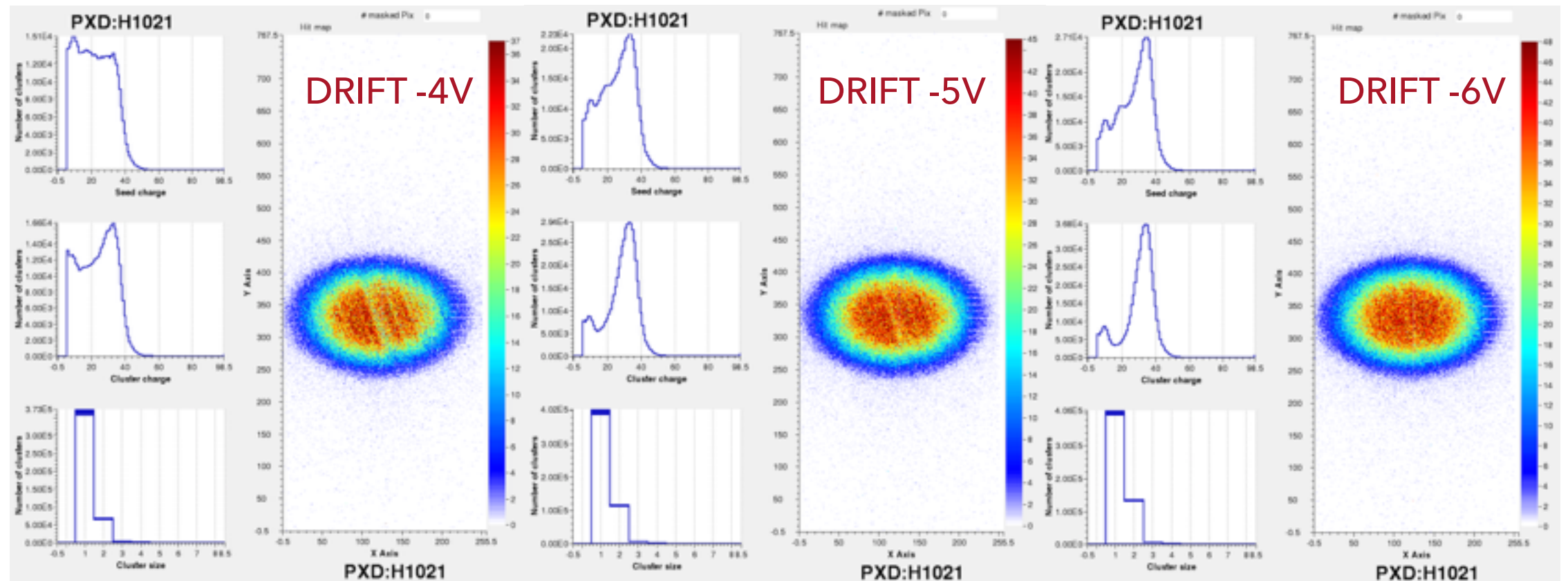


HV -60V

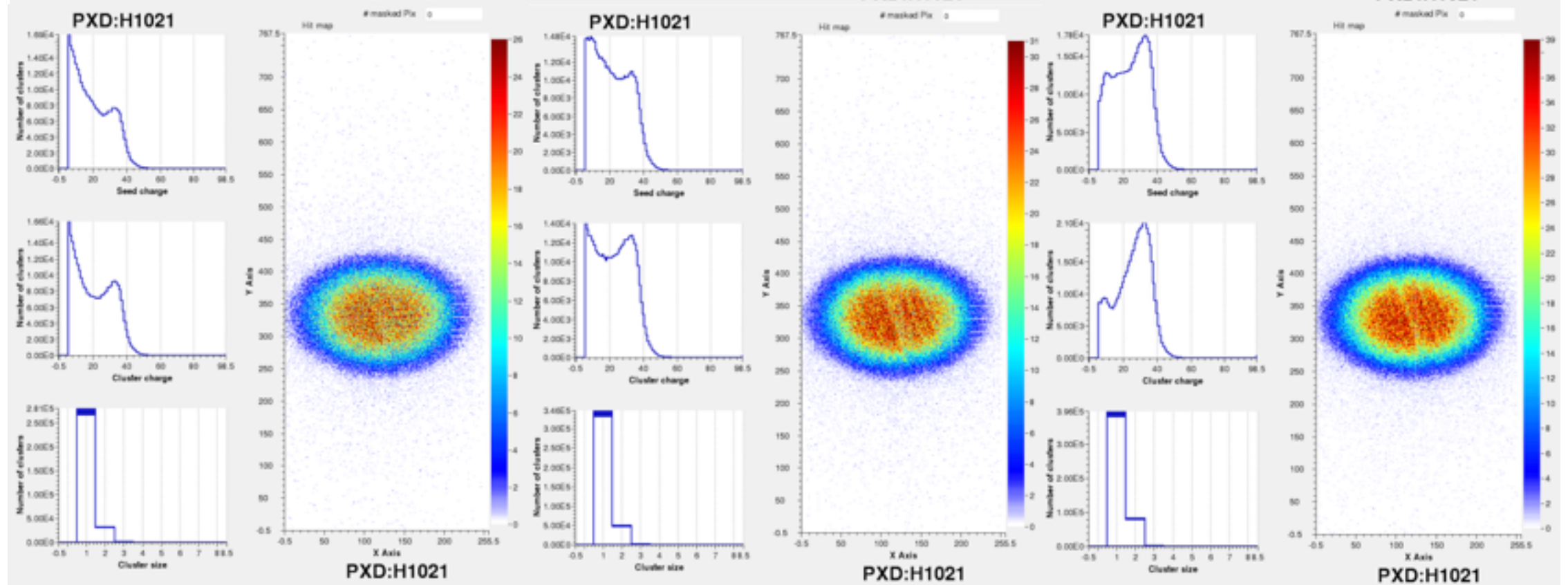
VOLTAGE SCAN: HV -64V, -68V

6

HV -64V



HV -68V



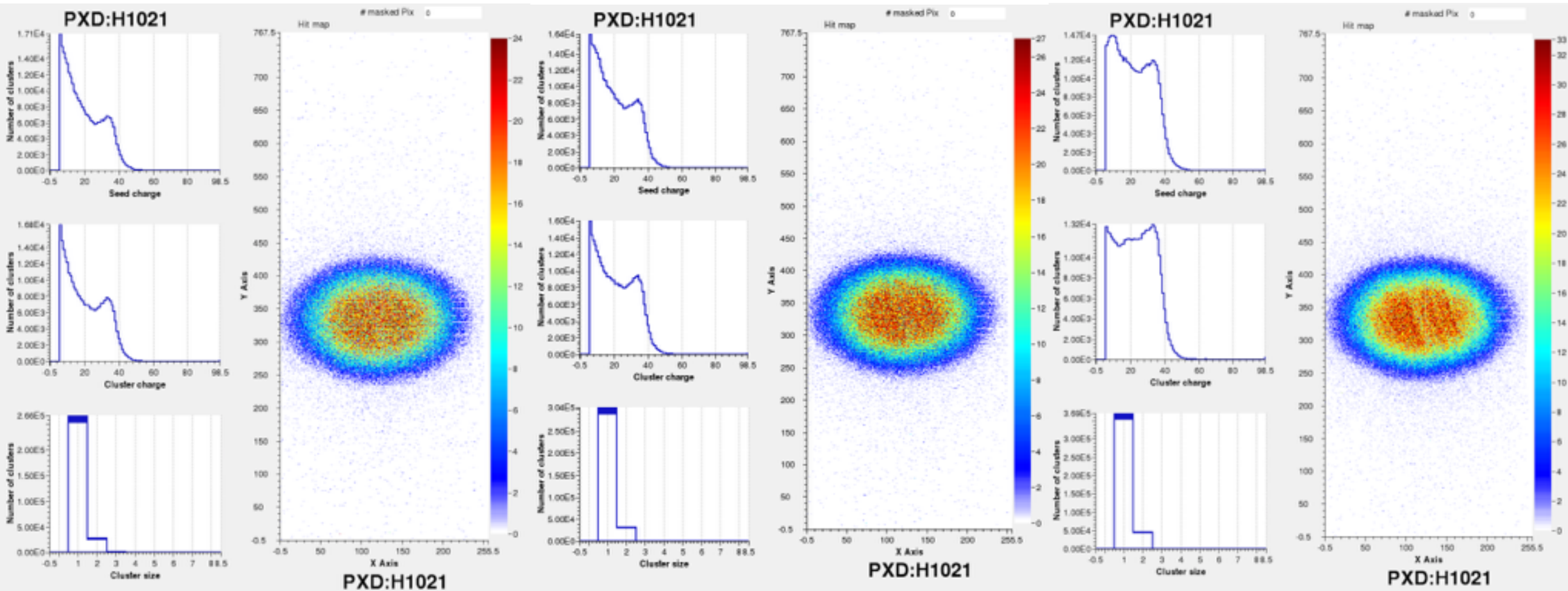
VOLTAGE SCAN: HV -72V

7

DRIFT -4V

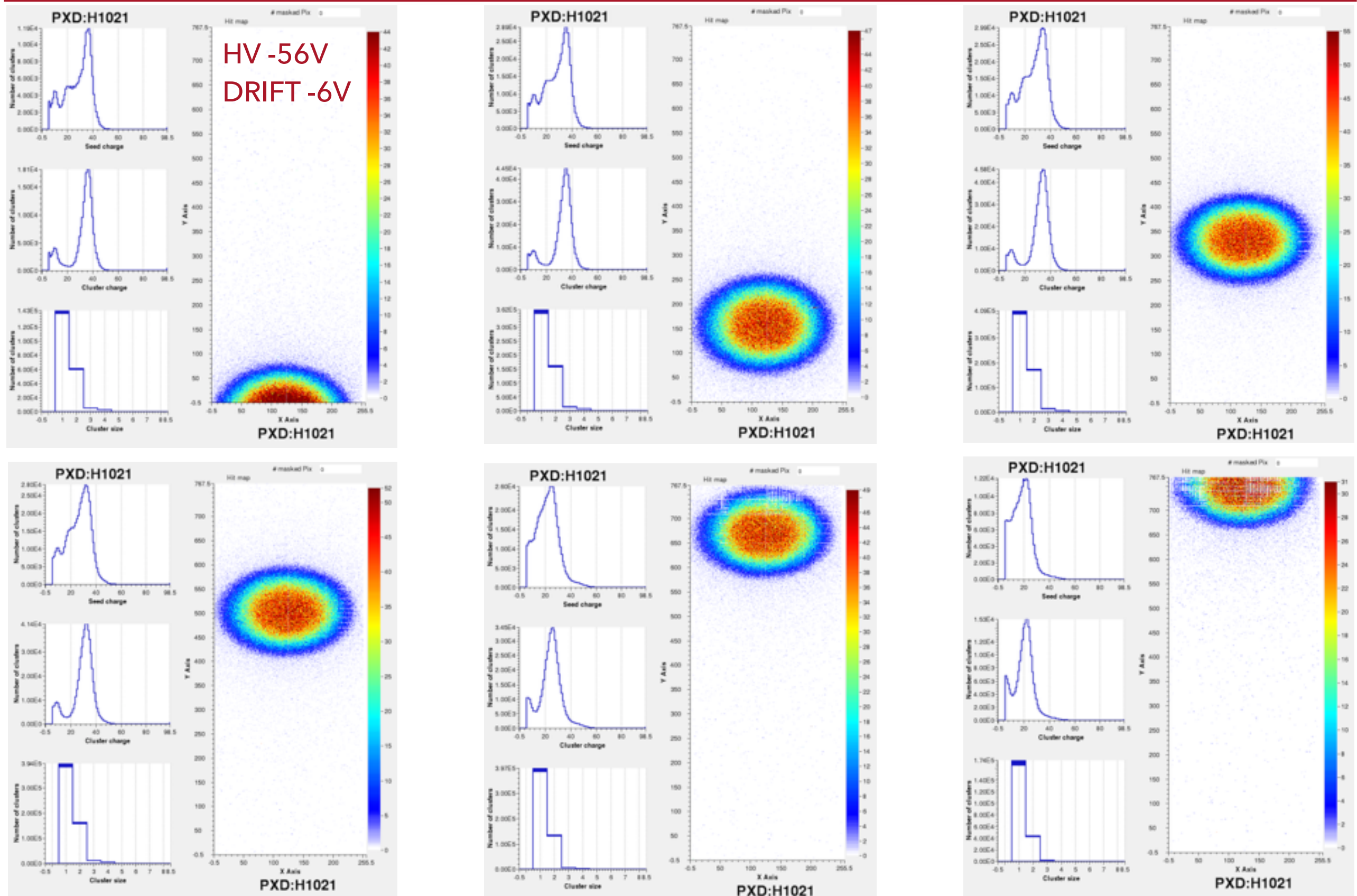
DRIFT -5V

DRIFT -6V



SPATIAL SCAN: MOVING THE SOURCE AROUND

8

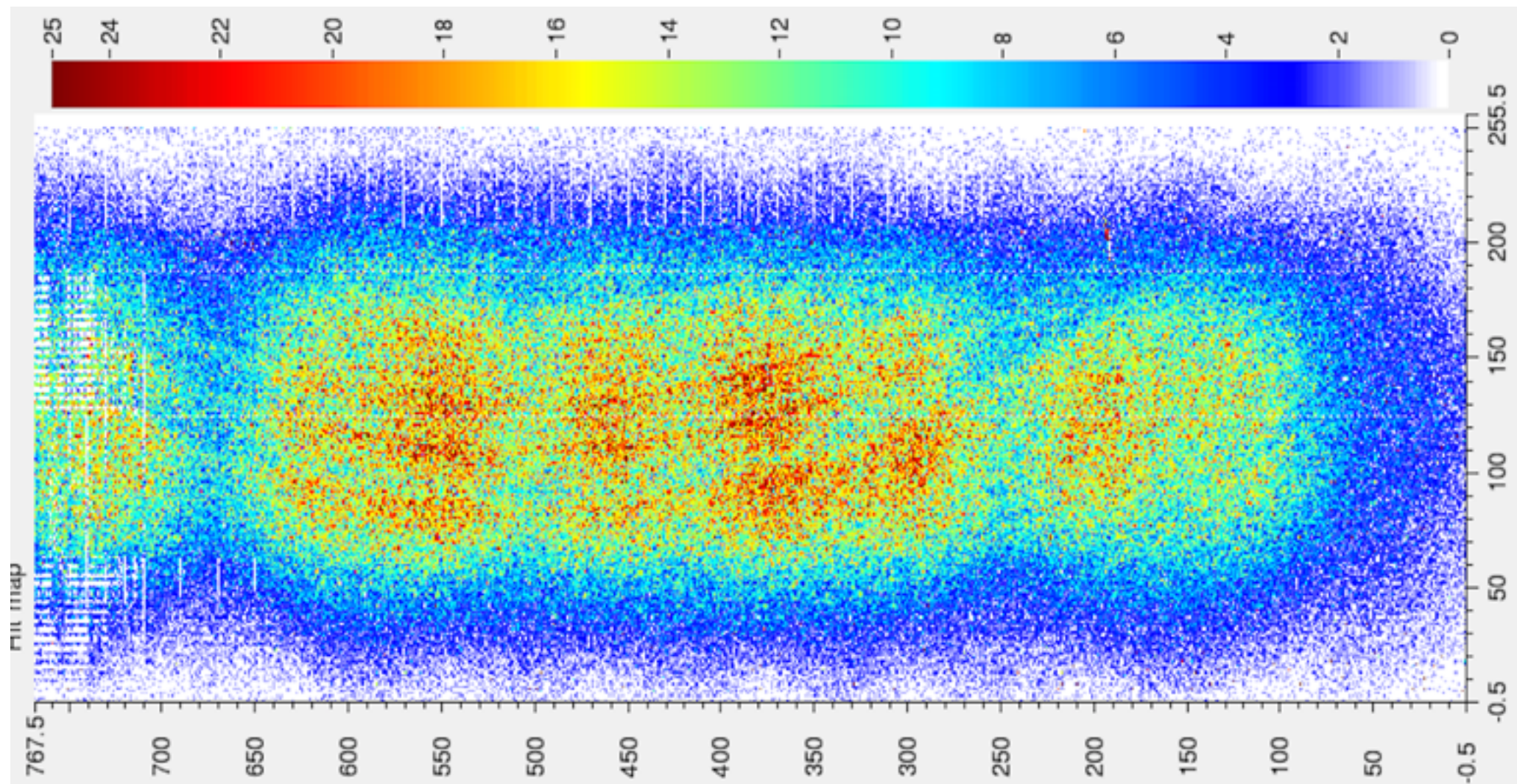


“SOURCE PAINTING”: LOOKING FOR THE RINGS

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HV -64V

DRIFT -4V

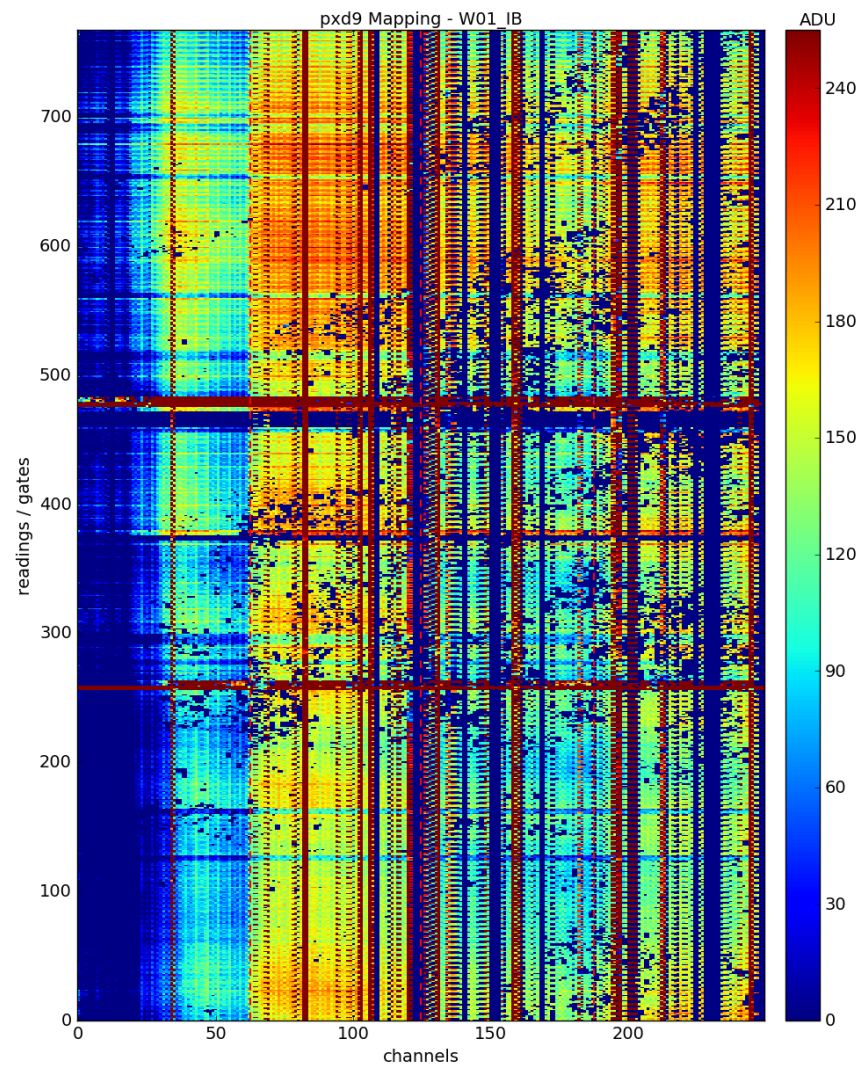
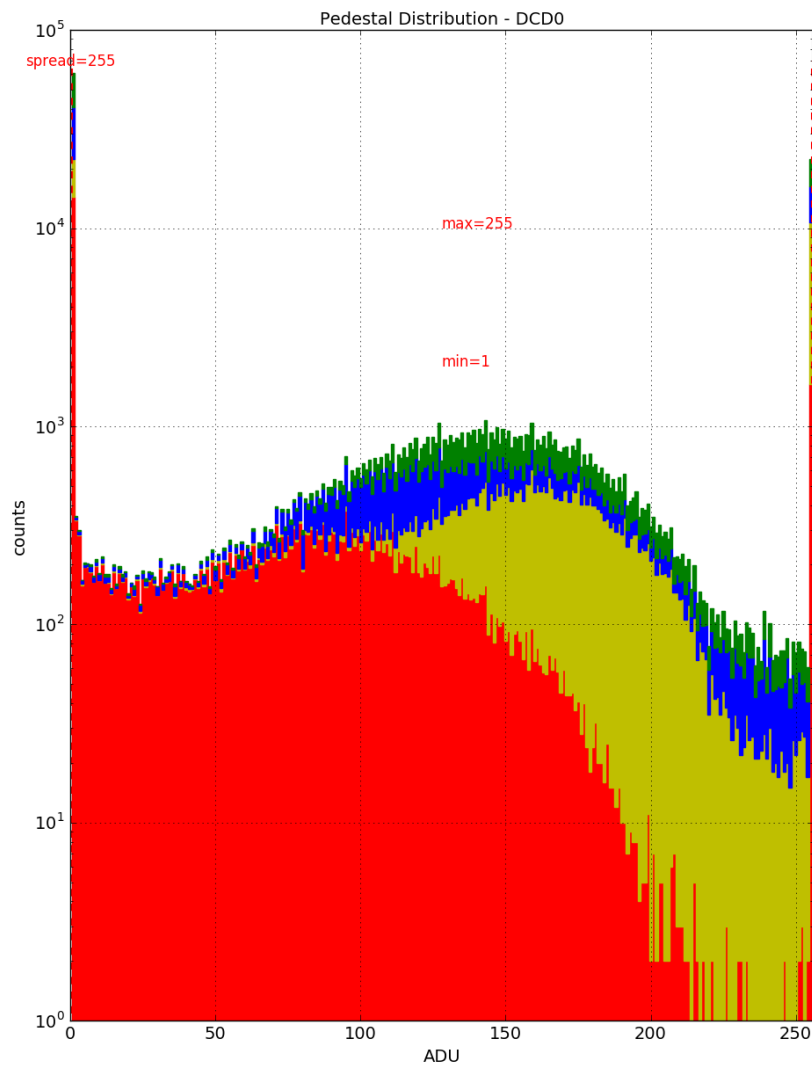




Phase 3 Module – W01_IB

Kapton with bad impedance line; anyway: all four links are stable

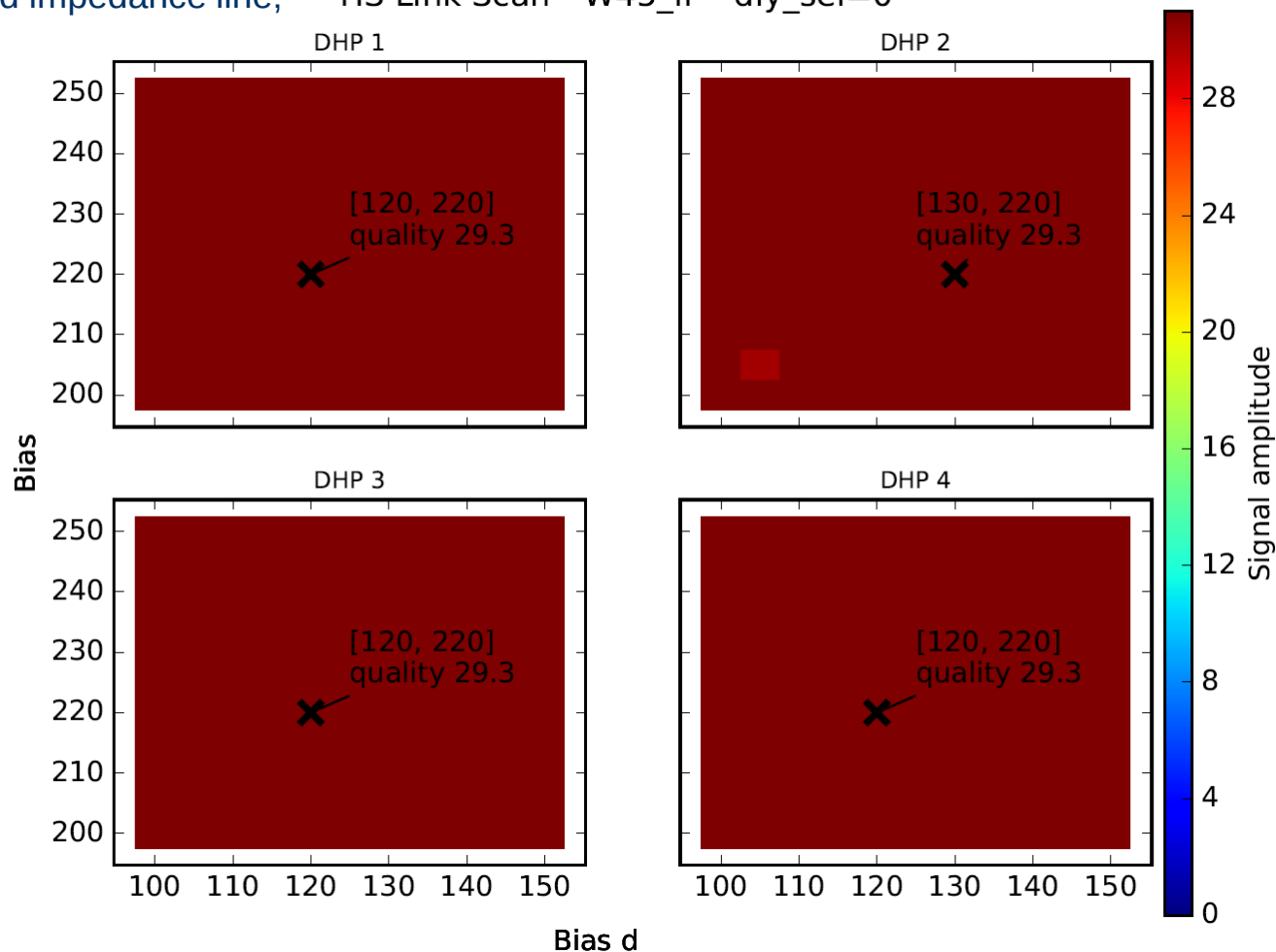
approximately 50 drain openings





Phase 3 Module – W45_IF

Kapton with bad impedance line; HS Link Scan - W45_IF - dly_sel=0

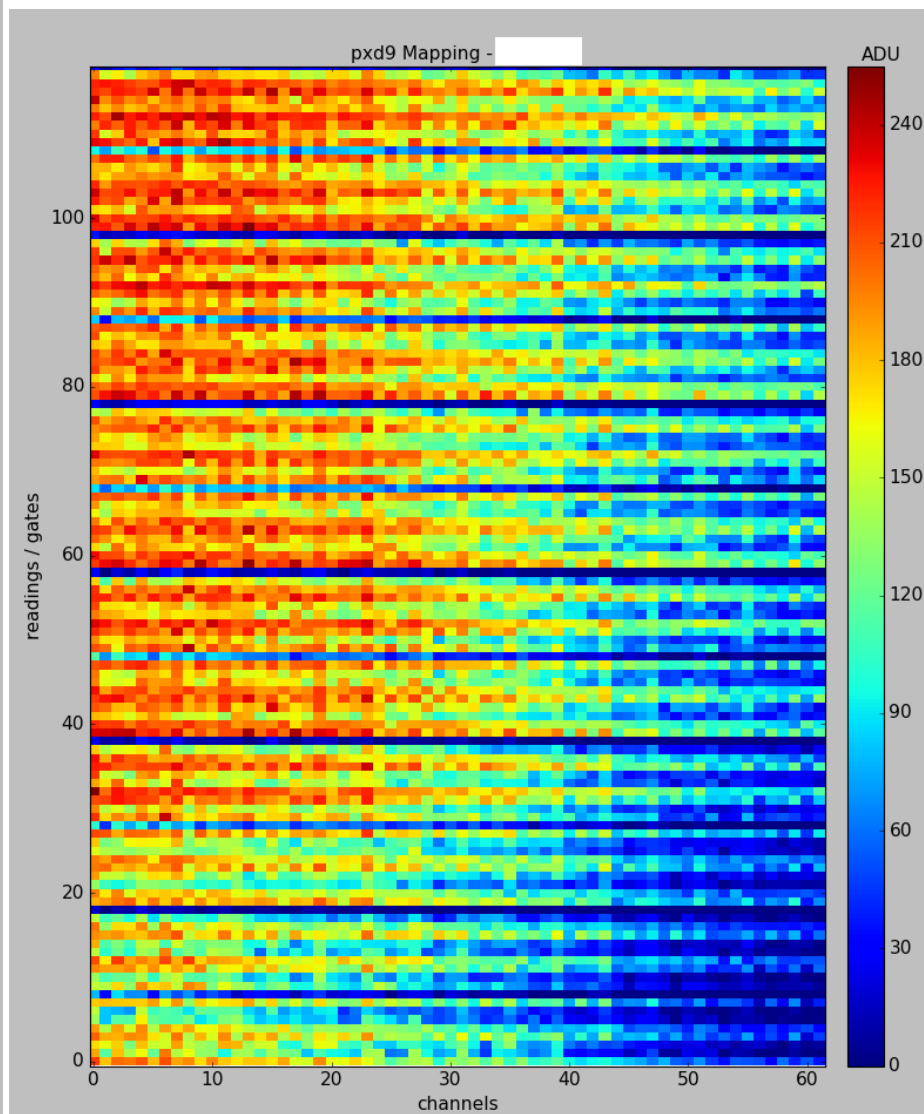
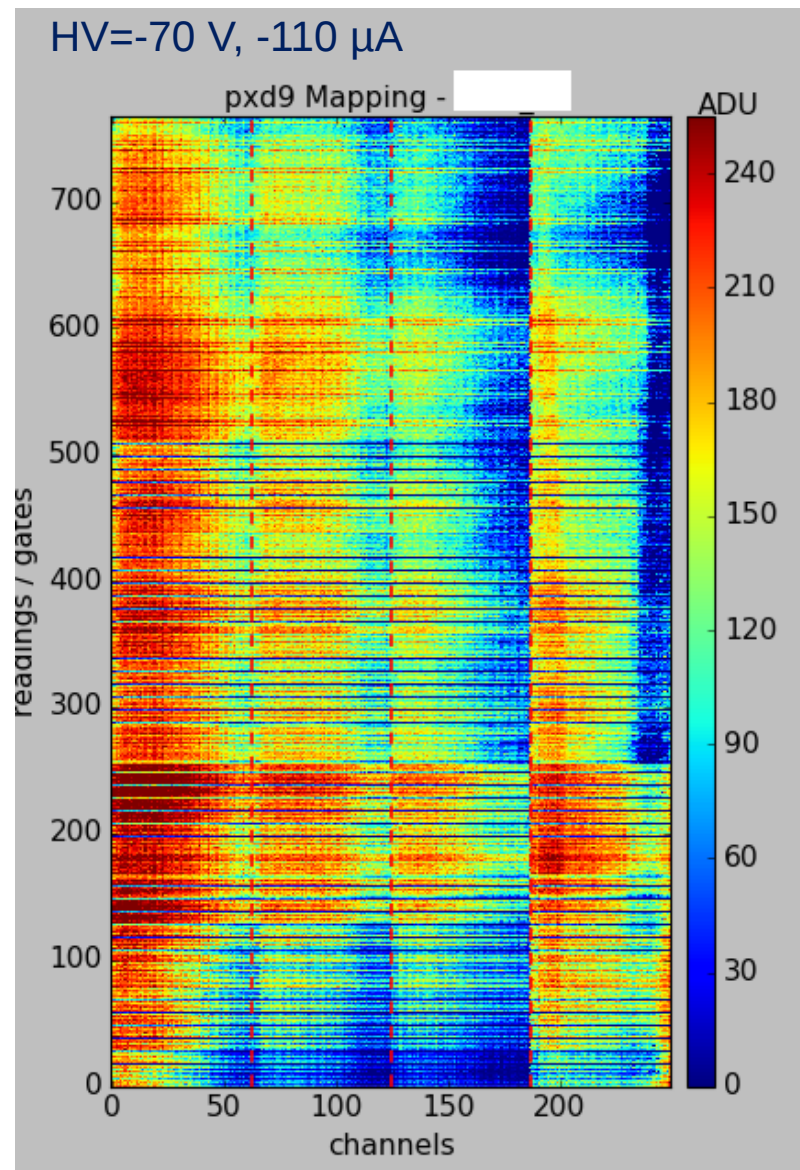


Matrix is under investigation



Phase 3 Module – W45_IF

Matrix is under investigation





to do

W37_OF1 source measurements

open topics:

- source measurement scripts – the ones used in online monitor; for reliable offline analysis, like S/N ratio, peak to valley, etc.
- not all scripts are well-developed according to the coding guidelines (offsets, sampling point curve, source measurements, gated mode)
- Problem: measuring and performing development (not quick and dirty) cannot be done simultaneously – ideas?



Services

Delivery:

4 Stück zum 11.08.17 (L1BWD, L1FWD, L2BWD, L2FWD)

4 Stück zum 31.08.17 (L1BWD, L1FWD, L2BWD, L2FWD)

Problems with

